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TOSHIBA Photo-IC Silicon Epitaxial Planar

TPS853

Mobile Phones, PHS
Notebook PCs, PDAs
Video cameras, Digital Still Cameras
Other Equipment Requiring Luminosity Adjustment

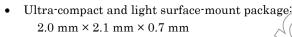
The TPS853 is an ultra-compact surface-mount photo-IC for illuminance sensors which incorporates a photodiode and current amp circuit in a single chip.

The sensitivity is superior to that of a phototransistor, and exhibits little variation.

It has spectral sensitivity closer to luminous efficiency and excellent output linearity.

This photo-IC can be used as the power-saving control for domestic appliances or for backlighting for displays in cellular phones.

This device includes stand-by function which can reduce the power consumption of the system.



- Excellent output linearity of illuminance
- Little fluctuation in light current and high level of sensitivity:

 $I_L = 37 \mu A$ to $74 \mu A$ @EV = 100 lx using fluorescent light

Light current variation width: ×1.67 (when light current classification is specified.)

Little temperature fluctuation in light current

- Built-in luminous-efficiency correction function, reduced sensitivity variations due to various light sources; IL (using incandescent light)/IL (using fluorescent light) = 1.2 (typ.)
- Low supply voltage, making device suitable for battery powered equipment: VCC = 2.2 V to 5.5 V

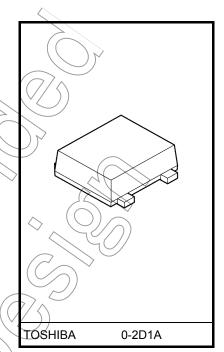
Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Supply voltage	Vcc	–0.5 to 7	V
Output voltage	Yout	≤V _{CC}	V
Stand-by voltage	V _{stb}	≤V _{CC}	V
Light current		5	mA
Permissible power dissipation	P	35	mW
Operating temperature range	Topr	-30 to 85	°C
Storage temperature range	T _{stg}	-40 to 100	°C
Soldering temperature range (Note 1)	> T _{sol}	260	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: The reflow time and the recommended temperature profile are shown in the section entitled Handling Precautions.



Weight: 0.0054 g (typ.)



Operating Ranges

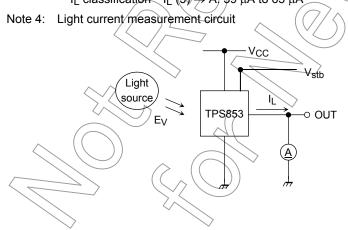
Characteristics	Symbol	Min	Тур.	Max	Unit
Supply voltage	V _{CC}	2.2	_	5.5	V
Stand-by voltage	V _{stb}	2.2	_	V _{CC}	V

Electrical and Optical Characteristics (Ta = 25°C)

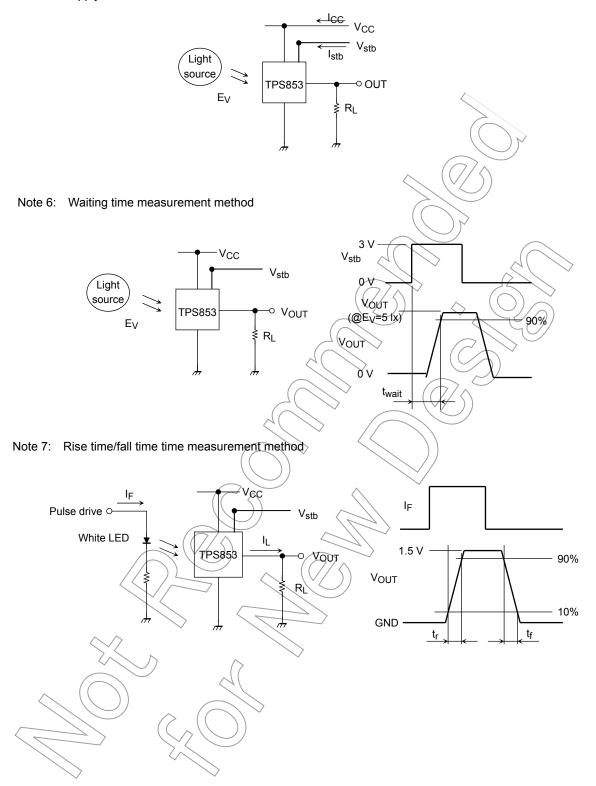
Charac	cteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Supply voltage		V _{CC}	-	2.2	_	5.5	V
Supply current (1)		I _{CC} +I _{stb} (1) (Note 6)	$V_{CC} = 3 \text{ V}, V_{stb} = 3 \text{ V}, E_V = 1000 \text{ lx}$ $R_L = 1 \text{ k}\Omega$ (Note 2). (Note 5)	\mathcal{L}	624	_	μА
Supply current (2)		I _{CC} +I _{stb} (2) (Note 6)	$\begin{aligned} & \text{V}_{CC} = 3 \text{ V}, \text{ V}_{stb} = 0.3 \text{ V}, \text{ E}_{V} = 1000 \text{ lx} \\ & \text{R}_{L} = 1 \text{ k}\Omega \end{aligned} \tag{Note 2}, \tag{Note 5}$	_	4.2	_	μА
Light current (1)		I _L (1)	V _{CC} = 3 V, V _{stb} = 3 V, E _V = 100 Jx (Note 2), (Note 4)		62	<u> </u>	μА
Light current (2)		I _L (2)	V _{CC} = 3 V, V _{stb} = 3 V, E _V = 10 lx (Note 3), (Note 4)	3.7	5.2	7.4	μΑ
Light current (3)		I _L (3)	V _{CC} = 3 V, V _{stb} = 3 V, E _V = 100 lx (Note 3), (Note 4)	37	52	74	μА
Light current ratio		<u>lL (1)</u> lL (3)			1.2	1.7	
Dark current		ILEAK	V _{CC} = 3.3 V, V _{stb} = 3 .3 V, E _V = 0	$\widetilde{}$	_	0.1	μΑ
Saturation output v	voltage	Vo <	$V_{CC} = 3$ V, $V_{stb} = 3$ V, $R_L = 150$ k Ω , $E_V = 100$ Jx (Note 3)	2.2	2.35		V
Peak sensitivity wa	avelength	λρ			600	_	nm
Switching time	Rise time	t _r	$V_{CC} = 3 \text{ V}, V_{stb} = 3 \text{ V}, R_{L} = 5 \text{ k}\Omega,$	_	0.07	1	ms
	Fall time	ti	V _{OUT} = 1.5 V (Note 7)	_	0.4	2	1113

Note 2: CIE standard A light source is used (color temperature = 2856K, approximated incandescence light).

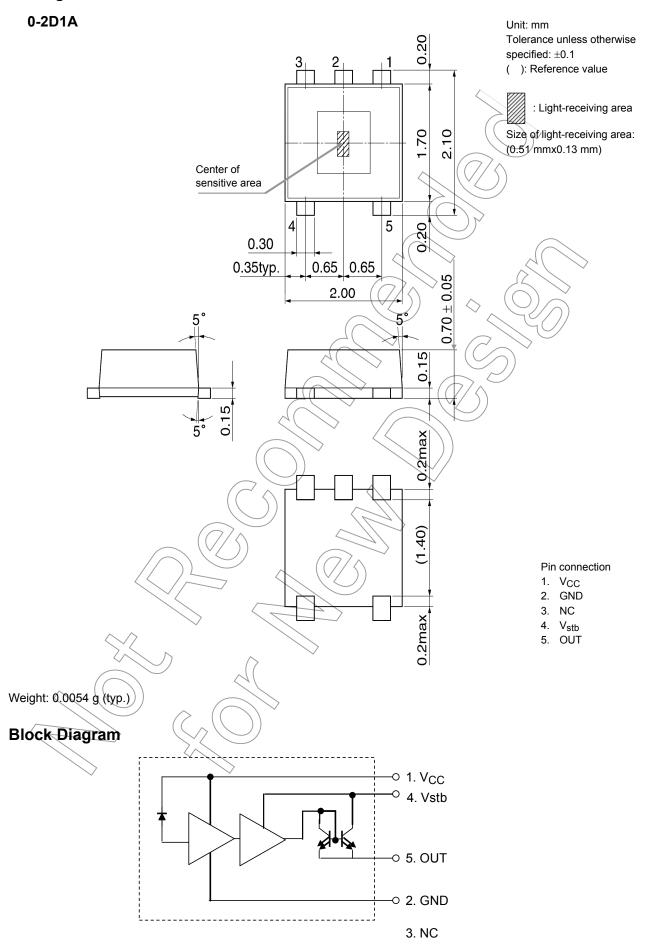
Note 3: Fluorescence light is used as light source. However, white LED is substituted in a mass-production process. IL classification I_L (3) \rightarrow A) 39 μ A to 65 μ A



Note 5: Supply current measurement circuit



Package Dimensions



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Handling Precautions

Insert a bypass condenser of up to $0.1\mu F$ between V_{cc} and GND near the device to stabilize the power supply line. It takes at least 200 ms when V_{cc}/V_{stb} are turned on at the same time or 100 ms when V_{stb} is turned on after V_{cc} is on for the internal circuit to stabilize. During this time the output signal is unstable. Please do not use the unstable signal as the output signal.

Moisture-Proof Packing

To avoid moisture absorption by the resin, the product is packed in an aluminum envelope with silica gel. Since the optical characteristics of the device can be affected during soldering by vaporization resulting from prior absorption of moisture and they should therefore be stored under the following conditions:

1. If the aluminum bag has been stored unopened

Temperature: 5 to 30°C

Relative humidity: 90% RH (max)

Time: 6 months

2. If the aluminum bag has been opened

Temperature: 5 to 30°C

Relative humidity: 70% RH (max)

Time: 168 h

3. Baking should be conducted within 72 h after the humidity indicator shows > 30% or the bag seal date is over 6 months. The number of baking should be once. If the baking is conducted repeatedly, it may affect the peel-back force and cause a problem for mounting.

Baking condition: 60 ± 5 °C, 12 to 24 h

Storage period: 12 months from the seal date on the label

- 4. When the photointerrupter is baked, protect it from electrostatic discharges
- 5. Do not toss or drop to avoid damaging the moisture-proof bag.

Mounting Precautions

TPS853 uses a clear resin, and delicate handling is necessary for it.

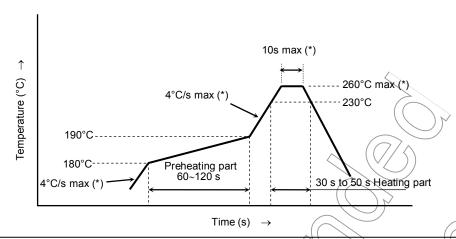
The characteristic change or the product might be damaged by the handling method of mounting. Please note the following and handle the product.

- Do not apply stress to the resin at high temperature. Time until the product returns at the normal temperature after mounting of the reflow is different according to the mounting substrate and the environment. Please do not give the stress with heat remained in the product.
- (2) The resin part is easily scratched, so avoid friction with hard materials.
- (3) When installing the assembly board in equipment, ensure that this product does not come into contact with other components.
- (4) Please confirm the heat contraction of the substrate of the reflow mounting doesn't influence the product. The load is given to the product by mounting that the heat contraction is large on the substrate and the installation position of the substrate. Please note that the characteristic changes or the product might be damaged.



Mounting Methods

(1) Example of reflow soldering



(*)The product is evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than MAX values) as an evaluation.

Please perform reflow soldering under the above conditions. Perform reflow soldering no more than twice.

- Please perform the first reflow soldering within 168 h after opening the package with reference to the above temperature profile.
- · Second reflow soldering

In case of second reflow soldering, it should be performed within 168 h after first reflow under the above conditions.

Unit: mm

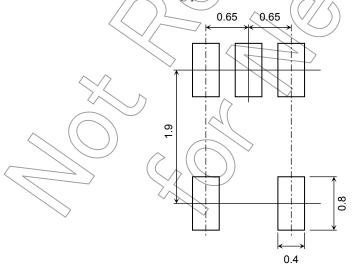
Storage conditions before second reflow soldering: 30°C, 70% RH or lower

- · Do not perform flow soldering.
- Make any necessary soldering correction manually.
 (do not do this more than once for any given pin.)

Temperature no more than 350°C (25 W for soldering iron)

Time: within 5 s

(2) Recommended soldering pattern



(3) Cleaning conditions

When cleaning is required after soldering

Chemicals: AK225 alcohol

Temperature and time: $50^{\circ}\text{C} \times 30 \text{ s or } 30^{\circ}\text{C} \times 3 \text{ minutes}$

Ultrasonic cleaning: 300 W or less

Packing Specification

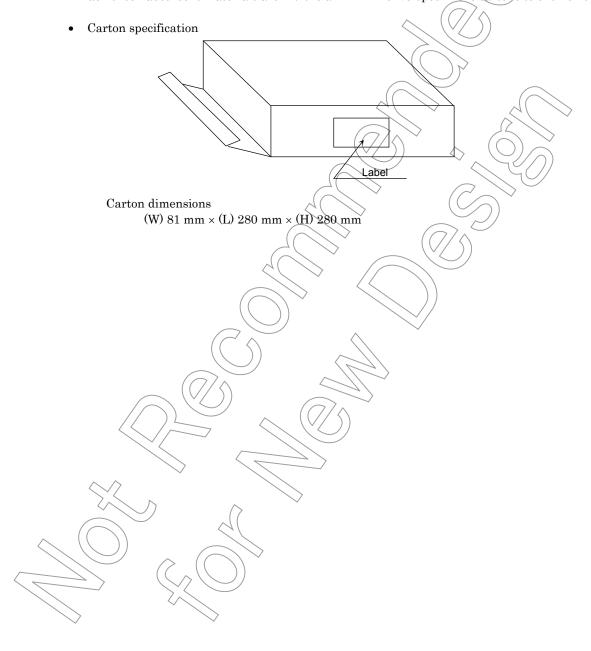
(1) Packing quantity

Reel (minimum packing quantity)	3,000 devices
Carton	5 reels (15,000 devices)

(2) Packing format

An aluminum envelope containing silica gel and reels is deaerated and sealed.

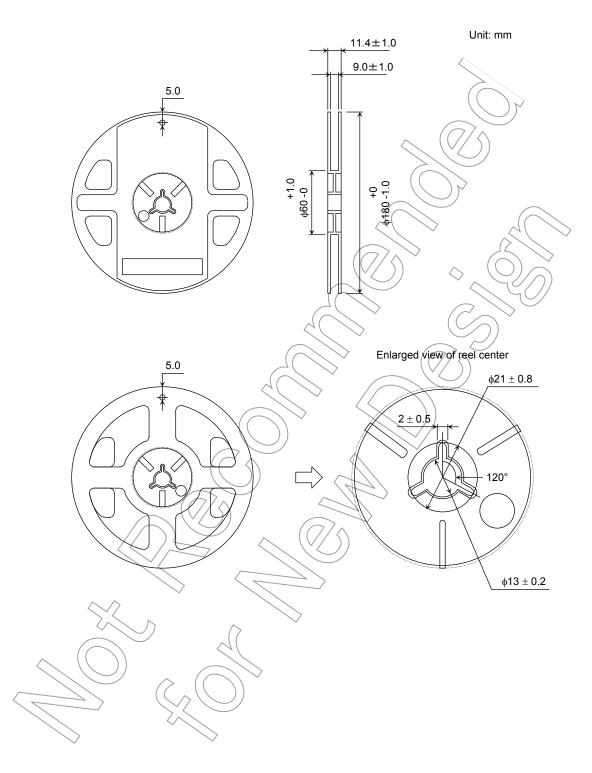
Pack shock-absorbent materials around the aluminum envelopes in the cartons to cushion them.



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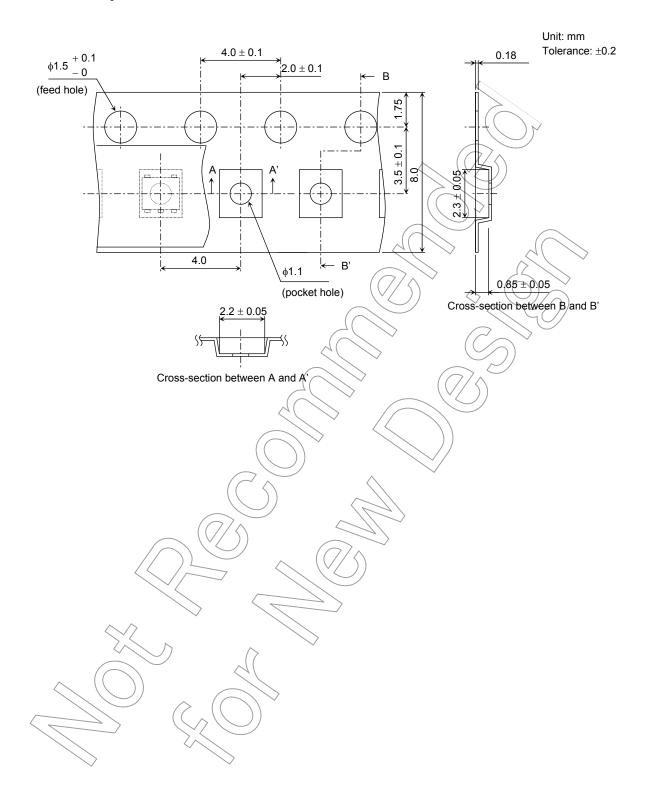
Tape Packing Specifications

(1) Reel dimensions Reel material: Plastic



(2) Tape dimensions

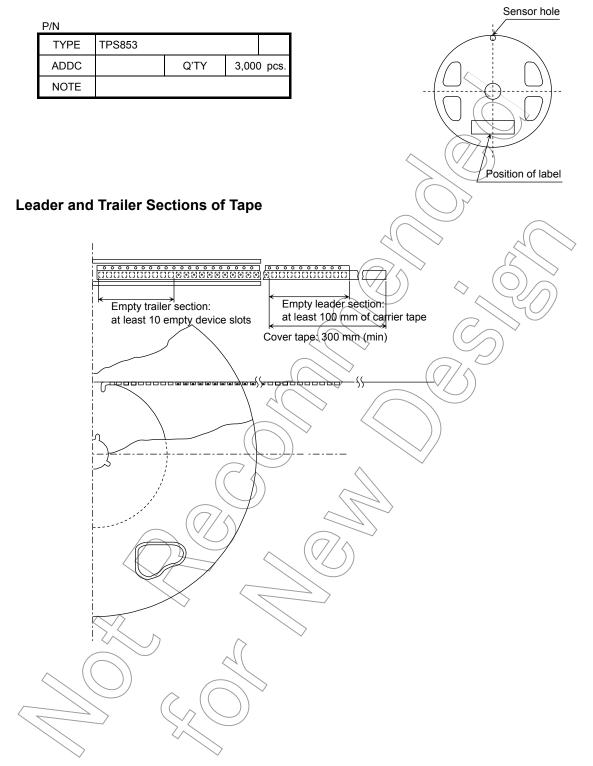
Tape material: Plastic (anti-electrostatic)

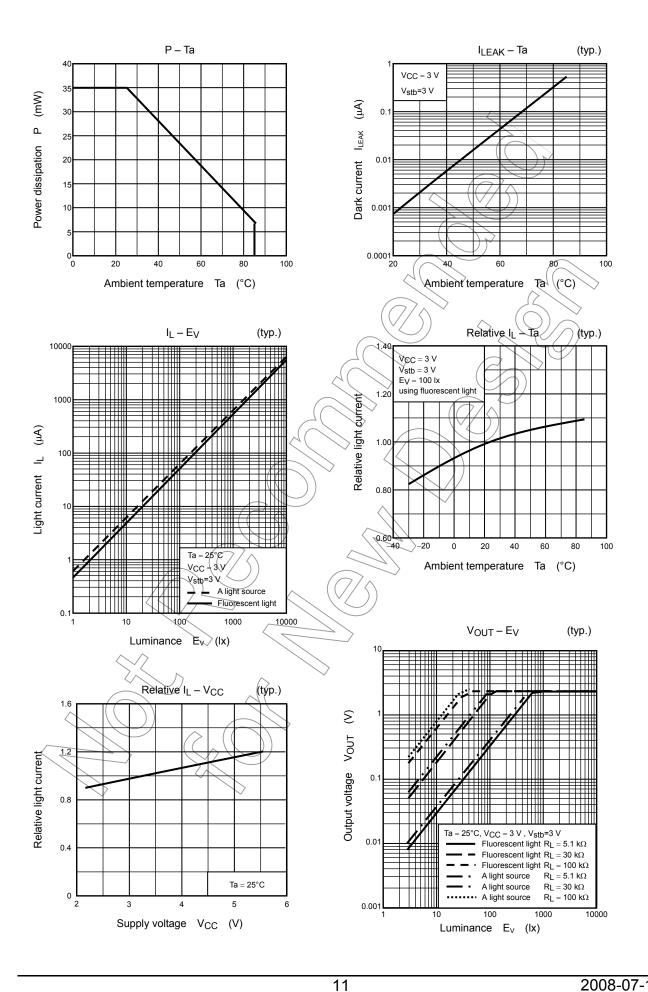


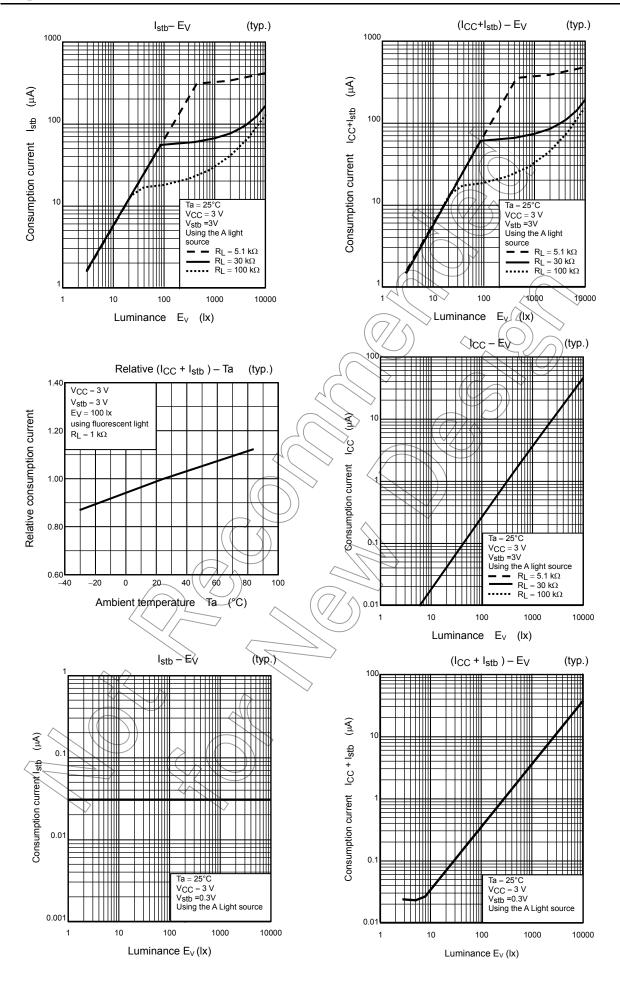


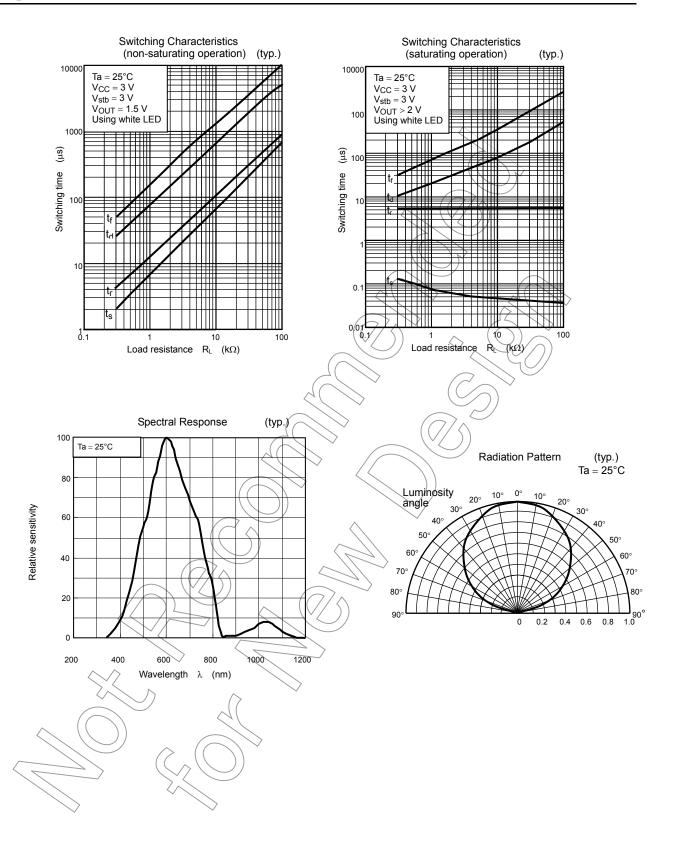
Reel Label

The label markings may include product number, tape type and quantity.









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